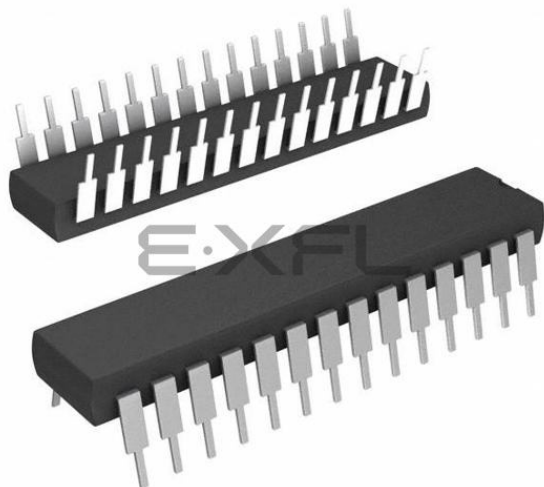




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Details

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	30 MIPS
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, QEI, POR, PWM, WDT
Number of I/O	20
Program Memory Size	12KB (4K x 24)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic30f2010-30i-sp

2.2 Programmer's Model

The programmer's model is shown in Figure 2-1 and consists of 16 x 16-bit working registers (W0 through W15), 2 x 40-bit accumulators (ACCA and ACCB), STATUS Register (SR), Data Table Page register (TBLPAG), Program Space Visibility Page register (PSVPAG), DO and REPEAT registers (DOSTART, DOEND, DCOUNT and RCOUNT) and Program Counter (PC). The working registers can act as data, address or offset registers. All registers are memory mapped. W0 acts as the W register for file register addressing.

Some of these registers have a shadow register associated with each of them, as shown in Figure 2-1. The shadow register is used as a temporary holding register and can transfer its contents to or from its host register upon the occurrence of an event. None of the shadow registers are accessible directly. The following rules apply for transfer of registers into and out of shadows.

- PUSH.S and POP.S
W0, W1, W2, W3, SR (DC, N, OV, Z and C bits only) are transferred.
- DO instruction
DOSTART, DOEND, DCOUNT shadows are pushed on loop start, and popped on loop end.

When a byte operation is performed on a working register, only the Least Significant Byte (LSB) of the target register is affected. However, a benefit of memory mapped working registers is that both the Least and Most Significant Bytes can be manipulated through byte wide data memory space accesses.

2.2.1 SOFTWARE STACK POINTER/ FRAME POINTER

The dsPIC[®] DSC devices contain a software stack. W15 is the dedicated software Stack Pointer (SP), and will be automatically modified by exception processing and subroutine calls and returns. However, W15 can be referenced by any instruction in the same manner as all other W registers. This simplifies the reading, writing and manipulation of the Stack Pointer (e.g., creating stack frames).

Note: In order to protect against misaligned stack accesses, W15<0> is always clear.

W15 is initialized to 0x0800 during a Reset. The user may reprogram the SP during initialization to any location within data space.

W14 has been dedicated as a Stack Frame Pointer as defined by the LNK and ULNK instructions. However, W14 can be referenced by any instruction in the same manner as all other W registers.

2.2.2 STATUS REGISTER

The dsPIC DSC core has a 16-bit STATUS Register (SR), the LSB of which is referred to as the SR Low Byte (SRL) and the MSB as the SR High Byte (SRH). See Figure 2-1 for SR layout.

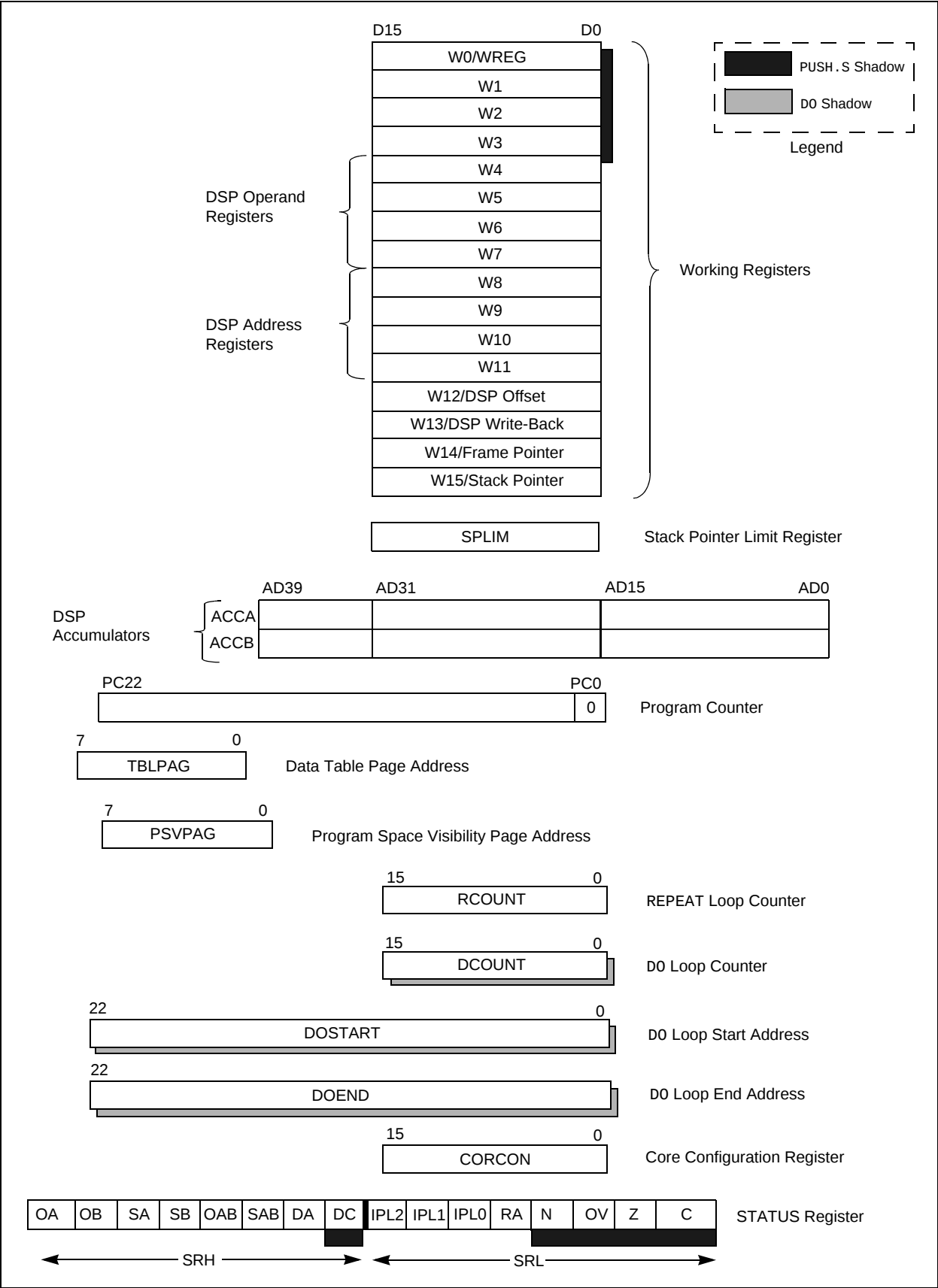
SRL contains all the MCU ALU operation status flags (including the Z bit), as well as the CPU Interrupt Priority Level status bits, IPL<2:0>, and the REPEAT active status bit, RA. During exception processing, SRL is concatenated with the MSB of the PC to form a complete word value which is then stacked.

The upper byte of the STATUS register contains the DSP adder/subtractor status bits, the DO Loop Active bit (DA) and the Digit Carry (DC) status bit.

2.2.3 PROGRAM COUNTER

The Program Counter is 23 bits wide. Bit 0 is always clear. Therefore, the PC can address up to 4M instruction words.

FIGURE 2-1: PROGRAMMER'S MODEL



4.2.3 MODULO ADDRESSING APPLICABILITY

Modulo addressing can be applied to the effective address calculation associated with any W register. It is important to realize that the address boundaries check for addresses less than or greater than the upper (for incrementing buffers) and lower (for decrementing buffers) boundary addresses (not just equal to). Address changes may, therefore, jump beyond boundaries and still be adjusted correctly.

Note: The modulo corrected effective address is written back to the register only when Pre-Modify or Post-Modify Addressing mode is used to compute the effective address. When an address offset (e.g., $[W7 + W2]$) is used, modulo address correction is performed, but the contents of the register remains unchanged.

If the length of a bit-reversed buffer is $M = 2^N$ bytes, then the last 'N' bits of the data buffer start address must be zeros.

$XB<14:0>$ is the bit-reversed address modifier or 'pivot point' which is typically a constant. In the case of an FFT computation, its value is equal to half of the FFT data buffer size.

Note: All Bit-Reversed EA calculations assume word-sized data (LSb of every EA is always clear). The XB value is scaled accordingly to generate compatible (byte) addresses.

When enabled, Bit-Reversed Addressing will only be executed for register indirect with pre-increment or post-increment addressing and word-sized data writes. It will not function for any other addressing mode or for byte-sized data, and normal addresses will be generated instead. When Bit-Reversed Addressing is active, the W Address Pointer will always be added to the address modifier (XB) and the offset associated with the register Indirect Addressing mode will be ignored. In addition, as word-sized data is a requirement, the LSb of the EA is ignored (and always clear).

Note: Modulo addressing and Bit-Reversed Addressing should not be enabled together. In the event that the user attempts to do this, bit reversed addressing will assume priority when active for the X WAGU, and X WAGU Modulo Addressing will be disabled. However, Modulo Addressing will continue to function in the X RAGU.

4.3 Bit-Reversed Addressing

Bit-Reversed Addressing is intended to simplify data reordering for radix-2 FFT algorithms. It is supported by the X AGU for data writes only.

The modifier, which may be a constant value or register contents, is regarded as having its bit order reversed. The address source and destination are kept in normal order. Thus, the only operand requiring reversal is the modifier.

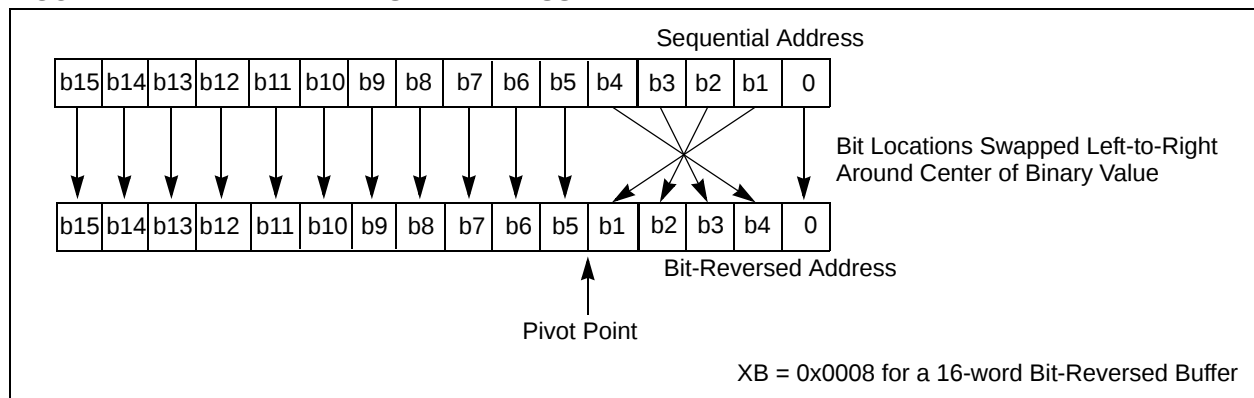
4.3.1 BIT-REVERSED ADDRESSING IMPLEMENTATION

Bit-Reversed Addressing is enabled when:

1. BWM (W register selection) in the MODCON register is any value other than 15 (the stack can not be accessed using Bit-Reversed Addressing) **and**
2. the BREN bit is set in the XBREV register **and**
3. the Addressing mode used is Register Indirect with Pre-Increment or Post-Increment.

If Bit-Reversed Addressing has already been enabled by setting the BREN ($XBREV<15>$) bit, then a write to the XBREV register should not be immediately followed by an indirect read operation using the W register that has been designated as the bit-reversed pointer.

FIGURE 4-2: BIT-REVERSED ADDRESS EXAMPLE



6.6.3 LOADING WRITE LATCHES

Example 6-2 shows a sequence of instructions that can be used to load the 96 bytes of write latches. 32 TBLWTL and 32 TBLWTH instructions are needed to load the write latches selected by the table pointer.

EXAMPLE 6-2: LOADING WRITE LATCHES

```
; Set up a pointer to the first program memory location to be written
; program memory selected, and writes enabled
MOV    #0x0000,W0                ;
MOV    W0,TBLPAG                 ; Initialize PM Page Boundary SFR
MOV    #0x6000,W0                ; An example program memory address
; Perform the TBLWT instructions to write the latches
; 0th_program_word
MOV    #LOW_WORD_0,W2            ;
MOV    #HIGH_BYTE_0,W3          ;
TBLWTL W2,[W0]                  ; Write PM low word into program latch
TBLWTH W3,[W0++]                ; Write PM high byte into program latch
; 1st_program_word
MOV    #LOW_WORD_1,W2            ;
MOV    #HIGH_BYTE_1,W3          ;
TBLWTL W2,[W0]                  ; Write PM low word into program latch
TBLWTH W3,[W0++]                ; Write PM high byte into program latch
; 2nd_program_word
MOV    #LOW_WORD_2,W2            ;
MOV    #HIGH_BYTE_2,W3          ;
TBLWTL W2,[W0]                  ; Write PM low word into program latch
TBLWTH W3,[W0++]                ; Write PM high byte into program latch
.
.
.
; 31st_program_word
MOV    #LOW_WORD_31,W2           ;
MOV    #HIGH_BYTE_31,W3         ;
TBLWTL W2,[W0]                  ; Write PM low word into program latch
TBLWTH W3,[W0++]                ; Write PM high byte into program latch
```

Note: In Example 6-2, the contents of the upper byte of W3 has no effect.

6.6.4 INITIATING THE PROGRAMMING SEQUENCE

For protection, the write initiate sequence for NVMKEY must be used to allow any erase or program operation to proceed. After the programming command has been executed, the user must wait for the programming time until programming is complete. The two instructions following the start of the programming sequence should be NOPs.

EXAMPLE 6-3: INITIATING A PROGRAMMING SEQUENCE

```
DISI    #5                        ; Block all interrupts with priority <7
                                   ; for next 5 instructions
MOV     #0x55,W0
MOV     W0,NVMKEY                 ; Write the 0x55 key
MOV     #0xAA,W1
MOV     W1,NVMKEY                 ; Write the 0xAA key
BSET    NVMCON,#WR               ; Start the erase sequence
NOP     ; Insert two NOPs after the erase
NOP     ; command is asserted
```

TABLE 11-1: INPUT CAPTURE REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
IC1BUF	0140	Input 1 Capture Register																uuuu uuuu uuuu uuuu
IC1CON	0142	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI<1:0>	ICOV	ICBNE	ICM<2:0>				0000 0000 0000 0000
IC2BUF	0144	Input 2 Capture Register																uuuu uuuu uuuu uuuu
IC2CON	0146	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI<1:0>	ICOV	ICBNE	ICM<2:0>				0000 0000 0000 0000
IC3BUF	0148	Input 3 Capture Register																uuuu uuuu uuuu uuuu
IC3CON	014A	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI<1:0>	ICOV	ICBNE	ICM<2:0>				0000 0000 0000 0000
IC4BUF	014C	Input 4 Capture Register																uuuu uuuu uuuu uuuu
IC4CON	014E	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI<1:0>	ICOV	ICBNE	ICM<2:0>				0000 0000 0000 0000
IC5BUF	0150	Input 5 Capture Register																uuuu uuuu uuuu uuuu
IC5CON	0152	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI<1:0>	ICOV	ICBNE	ICM<2:0>				0000 0000 0000 0000
IC6BUF	0154	Input 6 Capture Register																uuuu uuuu uuuu uuuu
IC6CON	0156	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI<1:0>	ICOV	ICBNE	ICM<2:0>				0000 0000 0000 0000
IC7BUF	0158	Input 7 Capture Register																uuuu uuuu uuuu uuuu
IC7CON	015A	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI<1:0>	ICOV	ICBNE	ICM<2:0>				0000 0000 0000 0000
IC8BUF	015C	Input 8 Capture Register																uuuu uuuu uuuu uuuu
IC8CON	015E	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI<1:0>	ICOV	ICBNE	ICM<2:0>				0000 0000 0000 0000

Legend: u = uninitialized bit; — = unimplemented bit, read as '0'

Note: Refer to the “dsPIC30F Family Reference Manual” (DS70046) for descriptions of register bit fields.

TABLE 13-1: QEI REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
QEICON	0122	CNTERR	—	QEISIDL	INDX	UPDN	QEIM2	QEIM1	QEIM0	SWPAB	—	TQGATE	TQCKPS1	TQCKPS0	POSRES	TQCS	UPDN_SRC	0000 0000 0000 0000
DFLTCON	0124	—	—	—	—	—	IMV1	IMV0	CEID	QEOUT	QECK2	QECK1	QECK0	—	—	—	—	0000 0000 0000 0000
POSCNT	0126	Position Counter<15:0>																0000 0000 0000 0000
MAXCNT	0128	Maximun Count<15:0>																1111 1111 1111 1111

Legend: — = unimplemented bit, read as '0'
Note: Refer to the “dsPIC30F Family Reference Manual” (DS70046) for descriptions of register bit fields.

14.1.4 DOUBLE UPDATE MODE

In the Double Update mode (PTMOD<1:0> = 11), an interrupt event is generated each time the PTMR register is equal to zero, as well as each time a period match occurs. The postscaler selection bits have no effect in this mode of the timer.

The Double Update mode provides two additional functions to the user. First, the control loop bandwidth is doubled because the PWM duty cycles can be updated, twice per period. Second, asymmetrical center-aligned PWM waveforms can be generated, which are useful for minimizing output waveform distortion in certain motor control applications.

Note: Programming a value of 0x0001 in the period register could generate a continuous interrupt pulse, and hence, must be avoided.

14.1.5 PWM TIME BASE PRESCALER

The input clock to PTMR (Fosc/4), has prescaler options of 1:1, 1:4, 1:16 or 1:64, selected by control bits PTCKPS<1:0> in the PTCN SFR. The prescaler counter is cleared when any of the following occurs:

- a write to the PTMR register
- a write to the PTCN register
- any device Reset

The PTMR register is not cleared when PTCN is written.

14.1.6 PWM TIME BASE POSTSCALER

The match output of PTMR can optionally be post-scaled through a 4-bit postscaler (which gives a 1:1 to 1:16 scaling).

The postscaler counter is cleared when any of the following occurs:

- a write to the PTMR register
- a write to the PTCN register
- any device Reset

The PTMR register is not cleared when PTCN is written.

14.2 PWM Period

PTPER is a 15-bit register and is used to set the counting period for the PWM time base. PTPER is a double-buffered register. The PTPER buffer contents are loaded into the PTPER register at the following instances:

- Free Running and Single Shot modes: When the PTMR register is reset to zero after a match with the PTPER register.
- Up/Down Counting modes: When the PTMR register is zero.

The value held in the PTPER buffer is automatically loaded into the PTPER register when the PWM time base is disabled (PTEN = 0).

The PWM period can be determined using Equation 14-1:

EQUATION 14-1: PWM PERIOD

$$T_{PWM} = T_{CY} \cdot (PTPER + 1) \cdot \text{PTMR Prescale Value}$$

If the PWM time base is configured for one of the Up/Down Count modes, the PWM period is found using Equation 14-2.

EQUATION 14-2: PWM PERIOD (UP/DOWN COUNT MODE)

$$T_{PWM} = T_{CY} \cdot 2 \cdot (PTPER + 1) \cdot \text{PTMR Prescale Value}$$

The maximum resolution (in bits) for a given device oscillator and PWM frequency can be determined using Equation 14-3:

EQUATION 14-3: PWM RESOLUTION

$$\text{Resolution} = \frac{\log(2 \cdot T_{PWM}/T_{CY})}{\log(2)}$$

TABLE 14-1: PWM REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
PTCON	01C0	PTEN	—	PTSIDL	—	—	—	—	—	PTOPS<3:0>				PTCKPS<1:0>		PTMOD<1:0>		0000 0000 0000 0000
PTMR	01C2	PTDIR	PWM Timer Count Value															0000 0000 0000 0000
PTPER	01C4	—	PWM Time Base Period Register															0011 1111 1111 1111
SEVTCMP	01C6	SEVTDIR	PWM Special Event Compare Register															0000 0000 0000 0000
PWMCON1	01C8	—	—	—	—	—	PTMOD3	PTMOD2	PTMOD1	—	PEN3H	PEN2H	PEN1H	—	PEN3L	PEN2L	PEN1L	0000 0000 0111 0111
PWMCON2	01CA	—	—	—	—	SEVOPS<3:0>				—	—	—	—	—	IUE	OSYNC	UDIS	0000 0000 0000 0000
DTCON1	01CC	DTBPS<1:0>		DTB<5:0>					DTAPS<1:0>		Dead Time A Value							0000 0000 0000 0000
FLTACON	01D0	—	—	FAOV3H	FAOV3L	FAOV2H	FAOV2L	FAOV1H	FAOV1L	FLTAM	—	—	—	—	FAEN3	FAEN2	FAEN1	0000 0000 0000 0000
OVDCON	01D4	—	—	POVD3H	POVD3L	POVD2H	POVD2L	POVD1H	POVD1L	—	—	POUT3H	POUT3L	POUT2H	POUT2L	POUT1H	POUT1L	0011 1111 0000 0000
PDC1	01D6	PWM Duty Cycle 1 Register																0000 0000 0000 0000
PDC2	01D8	PWM Duty Cycle 2 Register																0000 0000 0000 0000
PDC3	01DA	PWM Duty Cycle 3 Register																0000 0000 0000 0000

Legend: — = unimplemented bit, read as '0'

Note: Refer to the “dsPIC30F Family Reference Manual” (DS70046) for descriptions of register bit fields.

15.3 Slave Select Synchronization

The $\overline{\text{SSx}}$ pin allows a Synchronous Slave mode. The SPI must be configured in SPI Slave mode, with $\overline{\text{SSx}}$ pin control enabled ($\text{SSEN} = 1$). When the $\overline{\text{SSx}}$ pin is low, transmission and reception are enabled, and the SDOx pin is driven. When $\overline{\text{SSx}}$ pin goes high, the SDOx pin is no longer driven. Also, the SPI module is re-synchronized, and all counters/control circuitry are reset. Therefore, when the $\overline{\text{SSx}}$ pin is asserted low again, transmission/reception will begin at the MSb, even if $\overline{\text{SSx}}$ had been de-asserted in the middle of a transmit/receive.

15.4 SPI Operation During CPU Sleep Mode

During Sleep mode, the SPI module is shut down. If the CPU enters Sleep mode while an SPI transaction is in progress, then the transmission and reception is aborted.

The transmitter and receiver will stop in Sleep mode. However, register contents are not affected by entering or exiting Sleep mode.

15.5 SPI Operation During CPU Idle Mode

When the device enters Idle mode, all clock sources remain functional. The SPISIDL bit ($\text{SPIxSTAT}\langle 13 \rangle$) selects if the SPI module will stop or continue on Idle. If $\text{SPISIDL} = 0$, the module will continue to operate when the CPU enters Idle mode. If $\text{SPISIDL} = 1$, the module will stop when the CPU enters Idle mode.

16.4.2 10-BIT MODE SLAVE RECEPTION

Once addressed, the master can generate a Repeated Start, reset the high byte of the address and set the R_W bit without generating a Stop bit, thus initiating a slave transmit operation.

16.5 Automatic Clock Stretch

In the Slave modes, the module can synchronize buffer reads and write to the master device by clock stretching.

16.5.1 TRANSMIT CLOCK STRETCHING

Both 10-bit and 7-bit Transmit modes implement clock stretching by asserting the SCLREL bit after the falling edge of the ninth clock if the TBF bit is cleared, indicating the buffer is empty.

In Slave Transmit modes, clock stretching is always performed, irrespective of the STREN bit.

Clock synchronization takes place following the ninth clock of the transmit sequence. If the device samples an ACK on the falling edge of the ninth clock, and if the TBF bit is still clear, then the SCLREL bit is automatically cleared. The SCLREL being cleared to '0' will assert the SCL line low. The user's ISR must set the SCLREL bit before transmission is allowed to continue. By holding the SCL line low, the user has time to service the ISR and load the contents of the I2CTRN before the master device can initiate another transmit sequence.

Note 1: If the user loads the contents of I2CTRN, setting the TBF bit before the falling edge of the ninth clock, the SCLREL bit will not be cleared and clock stretching will not occur.

2: The SCLREL bit can be set in software, regardless of the state of the TBF bit.

16.5.2 RECEIVE CLOCK STRETCHING

The STREN bit in the I2CCON register can be used to enable clock stretching in Slave Receive mode. When the STREN bit is set, the SCL pin will be held low at the end of each data receive sequence.

16.5.3 CLOCK STRETCHING DURING 7-BIT ADDRESSING (STREN = 1)

When the STREN bit is set in Slave Receive mode, the SCL line is held low when the buffer register is full. The method for stretching the SCL output is the same for both 7 and 10-bit Addressing modes.

Clock stretching takes place following the ninth clock of the receive sequence. On the falling edge of the ninth clock at the end of the ACK sequence, if the RBF bit is set, the SCLREL bit is automatically cleared, forcing the SCL output to be held low. The user's ISR must set the SCLREL bit before reception is allowed to continue. By

holding the SCL line low, the user has time to service the ISR and read the contents of the I2CRCV before the master device can initiate another receive sequence. This will prevent buffer overruns from occurring.

Note 1: If the user reads the contents of the I2CRCV, clearing the RBF bit before the falling edge of the ninth clock, the SCLREL bit will not be cleared and clock stretching will not occur.

2: The SCLREL bit can be set in software, regardless of the state of the RBF bit. The user should be careful to clear the RBF bit in the ISR before the next receive sequence in order to prevent an overflow condition.

16.5.4 CLOCK STRETCHING DURING 10-BIT ADDRESSING (STREN = 1)

Clock stretching takes place automatically during the addressing sequence. Because this module has a register for the entire address, it is not necessary for the protocol to wait for the address to be updated.

After the address phase is complete, clock stretching will occur on each data receive or transmit sequence as was described earlier.

16.6 Software Controlled Clock Stretching (STREN = 1)

When the STREN bit is '1', the SCLREL bit may be cleared by software to allow software to control the clock stretching. The logic will synchronize writes to the SCLREL bit with the SCL clock. Clearing the SCLREL bit will not assert the SCL output until the module detects a falling edge on the SCL output and SCL is sampled low. If the SCLREL bit is cleared by the user while the SCL line has been sampled low, the SCL output will be asserted (held low). The SCL output will remain low until the SCLREL bit is set, and all other devices on the I²C bus have de-asserted SCL. This ensures that a write to the SCLREL bit will not violate the minimum high time requirement for SCL.

If the STREN bit is '0', a software write to the SCLREL bit will be disregarded and have no effect on the SCLREL bit.

16.7 Interrupts

The I²C module generates two interrupt flags, MI2CIF (I²C Master Interrupt Flag) and SI2CIF (I²C Slave Interrupt Flag). The MI2CIF interrupt flag is activated on completion of a master message event. The SI2CIF interrupt flag is activated on detection of a message directed to the slave.

16.8 Slope Control

The I²C standard requires slope control on the SDA and SCL signals for Fast Mode (400 kHz). The control bit, DISSLW, enables the user to disable slew rate control, if desired. It is necessary to disable the slew rate control for 1 MHz mode.

16.9 IPMI Support

The control bit IPMIEN enables the module to support Intelligent Peripheral Management Interface (IPMI). When this bit is set, the module accepts and acts upon all addresses.

16.10 General Call Address Support

The general call address can address all devices. When this address is used, all devices should, in theory, respond with an acknowledgement.

The general call address is one of eight addresses reserved for specific purposes by the I²C protocol. It consists of all 0s with R_W = 0.

The general call address is recognized when the General Call Enable (GCEN) bit is set (I2CCON<15> = 1). Following a Start bit detection, 8 bits are shifted into I2CRSR and the address is compared with I2CADD, and is also compared with the general call address which is fixed in hardware.

If a general call address match occurs, the I2CRSR is transferred to the I2CRCV after the eighth clock, the RBF flag is set, and on the falling edge of the ninth bit (ACK bit), the master event interrupt flag (MI2CIF) is set.

When the interrupt is serviced, the source for the interrupt can be checked by reading the contents of the I2CRCV to determine if the address was device specific, or a general call address.

16.11 I²C Master Support

As a Master device, six operations are supported.

- Assert a Start condition on SDA and SCL.
- Assert a Restart condition on SDA and SCL.
- Write to the I2CTRN register initiating transmission of data/address.
- Generate a Stop condition on SDA and SCL.
- Configure the I²C port to receive data.
- Generate an ACK condition at the end of a received byte of data.

16.12 I²C Master Operation

The master device generates all of the serial clock pulses and the Start and Stop conditions. A transfer is ended with a Stop condition or with a Repeated Start condition. Since the Repeated Start condition is also the beginning of the next serial transfer, the I²C bus will not be released.

In Master Transmitter mode, serial data is output through SDA, while SCL outputs the serial clock. The first byte transmitted contains the slave address of the receiving device (7 bits) and the data direction bit. In this case, the data direction bit (R_W) is logic '0'. Serial data is transmitted 8 bits at a time. After each byte is transmitted, an ACK bit is received. Start and Stop conditions are output to indicate the beginning and the end of a serial transfer.

In Master Receive mode, the first byte transmitted contains the slave address of the transmitting device (7 bits) and the data direction bit. In this case, the data direction bit (R_W) is logic '1'. Thus, the first byte transmitted is a 7-bit slave address, followed by a '1' to indicate receive bit. Serial data is received via SDA, while SCL outputs the serial clock. Serial data is received 8 bits at a time. After each byte is received, an ACK bit is transmitted. Start and Stop conditions indicate the beginning and end of transmission.

16.12.1 I²C MASTER TRANSMISSION

Transmission of a data byte, a 7-bit address or the second half of a 10-bit address is accomplished by simply writing a value to I2CTRN register. The user should only write to I2CTRN when the module is in a Wait state. This action will set the buffer full flag (TBF) and allow the Baud Rate Generator to begin counting and start the next transmission. Each bit of address/data will be shifted out onto the SDA pin after the falling edge of SCL is asserted. The Transmit Status Flag, TRSTAT (I2CSTAT<14>), indicates that a master transmit is in progress.

16.12.2 I²C MASTER RECEPTION

Master mode reception is enabled by programming the receive enable (RCEN) bit (I2CCON<11>). The I²C module must be Idle before the RCEN bit is set, otherwise the RCEN bit will be disregarded. The Baud Rate Generator begins counting, and on each rollover, the state of the SCL pin toggles, and data is shifted in to the I2CRSR on the rising edge of each clock.

16.12.3 BAUD RATE GENERATOR

In I²C Master mode, the reload value for the BRG is located in the I2CBRG register. When the BRG is loaded with this value, the BRG counts down to '0' and stops until another reload has taken place. If clock arbitration is taking place, for instance, the BRG is reloaded when the SCL pin is sampled high.

As per the I²C standard, FSCK may be 100 kHz or 400 kHz. However, the user can specify any baud rate up to 1 MHz. I2CBRG values of '0' or '1' are illegal.

EQUATION 16-1: I2CBRG VALUE

$$I2CBRG = \left(\frac{FCY}{FSCL} - \frac{FCY}{1, 111, 111} \right) - 1$$

TABLE 20-1: SYMBOLS USED IN OPCODE DESCRIPTIONS (CONTINUED)

Field	Description
Wb	Base W register $\in \{W0..W15\}$
Wd	Destination W register $\in \{Wd, [Wd], [Wd++] , [Wd--], [++Wd], [--Wd]\}$
Wdo	Destination W register $\in \{Wnd, [Wnd], [Wnd++] , [Wnd--], [++Wnd], [--Wnd], [Wnd+Wb]\}$
Wm, Wn	Dividend, Divisor working register pair (direct addressing)
Wm*Wm	Multiplicand and Multiplier working register pair for Square instructions $\in \{W4 * W4, W5 * W5, W6 * W6, W7 * W7\}$
Wm*Wn	Multiplicand and Multiplier working register pair for DSP instructions $\in \{W4 * W5, W4 * W6, W4 * W7, W5 * W6, W5 * W7, W6 * W7\}$
Wn	One of 16 working registers $\in \{W0..W15\}$
Wnd	One of 16 destination working registers $\in \{W0..W15\}$
Wns	One of 16 source working registers $\in \{W0..W15\}$
WREG	W0 (working register used in file register instructions)
Ws	Source W register $\in \{Ws, [Ws], [Ws++] , [Ws--], [++Ws], [--Ws]\}$
Wso	Source W register $\in \{Wns, [Wns], [Wns++] , [Wns--], [++Wns], [--Wns], [Wns+Wb]\}$
Wx	X data space prefetch address register for DSP instructions $\in \{[W8] + = 6, [W8] + = 4, [W8] + = 2, [W8], [W8] - = 6, [W8] - = 4, [W8] - = 2, [W9] + = 6, [W9] + = 4, [W9] + = 2, [W9], [W9] - = 6, [W9] - = 4, [W9] - = 2, [W9 + W12], \text{none}\}$
Wxd	X data space prefetch destination register for DSP instructions $\in \{W4..W7\}$
Wy	Y data space prefetch address register for DSP instructions $\in \{[W10] + = 6, [W10] + = 4, [W10] + = 2, [W10], [W10] - = 6, [W10] - = 4, [W10] - = 2, [W11] + = 6, [W11] + = 4, [W11] + = 2, [W11], [W11] - = 6, [W11] - = 4, [W11] - = 2, [W11 + W12], \text{none}\}$
Wyd	Y data space prefetch destination register for DSP instructions $\in \{W4..W7\}$

dsPIC30F2010

22.1 DC Characteristics

TABLE 22-1: OPERATING MIPS VS. VOLTAGE

VDD Range	Temp Range	Max MIPS	
		dsPIC30F2010-30I	dsPIC30F2010-20E
4.5-5.5V	-40°C to 85°C	30	—
4.5-5.5V	-40°C to 125°C	—	20
3.0-3.6V	-40°C to 85°C	20	—
3.0-3.6V	-40°C to 125°C	—	15
2.5-3.0V	-40°C to 85°C	10	—

TABLE 22-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
dsPIC30F2010-30I					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
dsPIC30F2010-20E					
Operating Junction Temperature Range	TJ	-40	—	+150	°C
Operating Ambient Temperature Range	TA	-40	—	+125	°C
Power Dissipation: Internal chip power dissipation: $P_{INT} = V_{DD} \times (I_{DD} - \sum I_{OH})$ I/O Pin power dissipation: $P_{I/O} = \sum (V_{DD} - V_{OH}) \times I_{OH} + \sum (V_{OL} \times I_{OL})$	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ - TA)/θJA			W

TABLE 22-3: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit	Notes
Package Thermal Resistance, 28-pin SOIC (SO)	θJA	48.3	—	°C/W	1
Package Thermal Resistance, 28-pin QFN	θJA	33.7	—	°C/W	1
Package Thermal Resistance, 28-pin SPDIP (SP)	θJA	42	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-ja (θJA) numbers are achieved by package simulations.

FIGURE 22-14: QEA/QEB INPUT CHARACTERISTICS

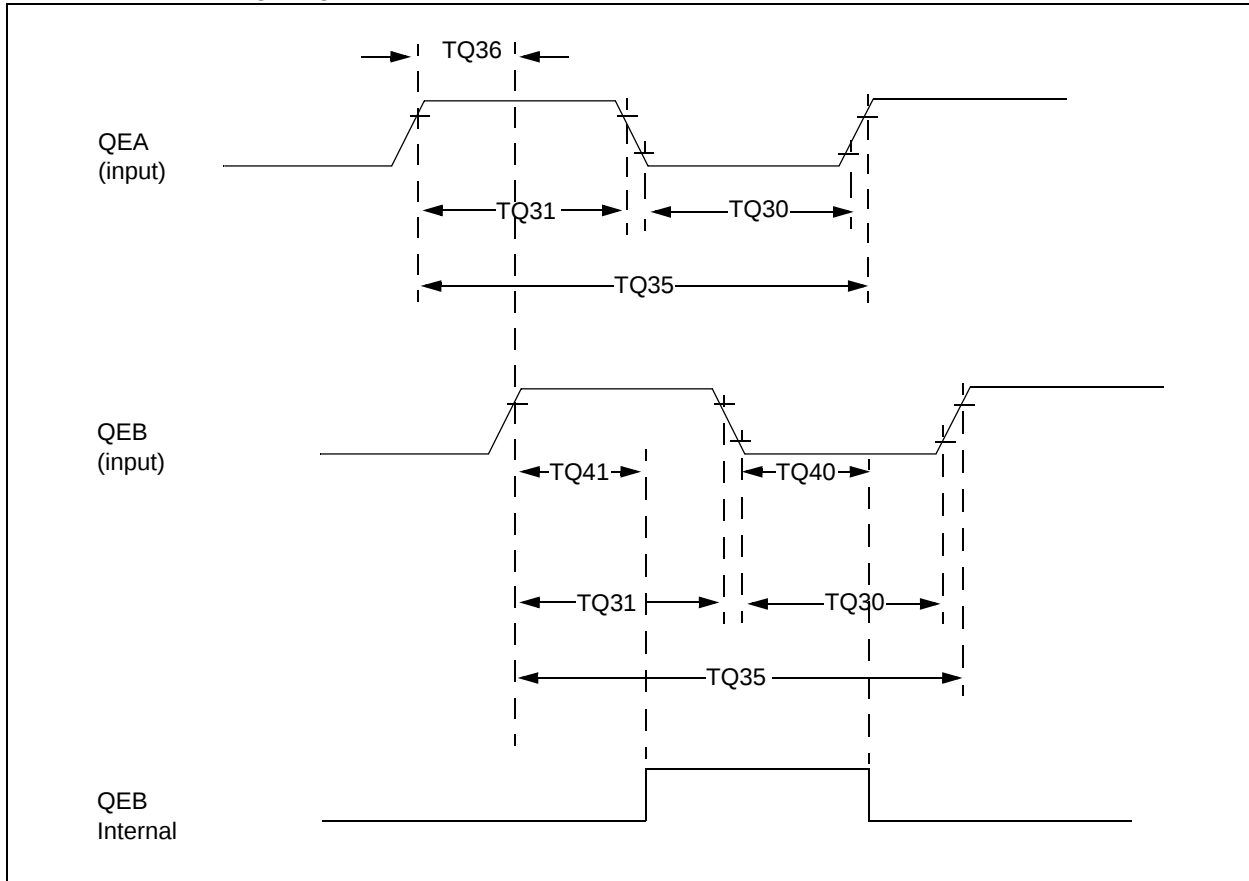


TABLE 22-30: QUADRATURE DECODER TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Param No.	Symbol	Characteristic ⁽¹⁾	Typ ⁽²⁾	Max	Units	Conditions
TQ30	TQuL	Quadrature Input Low Time	6 Tcy	—	ns	—
TQ31	TQuH	Quadrature Input High Time	6 Tcy	—	ns	—
TQ35	TQuIN	Quadrature Input Period	12 Tcy	—	ns	—
TQ36	TQuP	Quadrature Phase Period	3 Tcy	—	ns	—
TQ40	TQuFL	Filter Time to Recognize Low, with Digital Filter	3 * N * Tcy	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 (Note 2)
TQ41	TQuFH	Filter Time to Recognize High, with Digital Filter	3 * N * Tcy	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 (Note 2)

Note 1: These parameters are characterized but not tested in manufacturing.

Note 2: N = Index Channel Digital Filter Clock Divide Select Bits. Refer to **Section 16. “Quadrature Encoder Interface (QEI)”** (DS70063) in the “dsPIC30F Family Reference Manual” (DS70046).

FIGURE 22-15: QEI MODULE INDEX PULSE TIMING CHARACTERISTICS

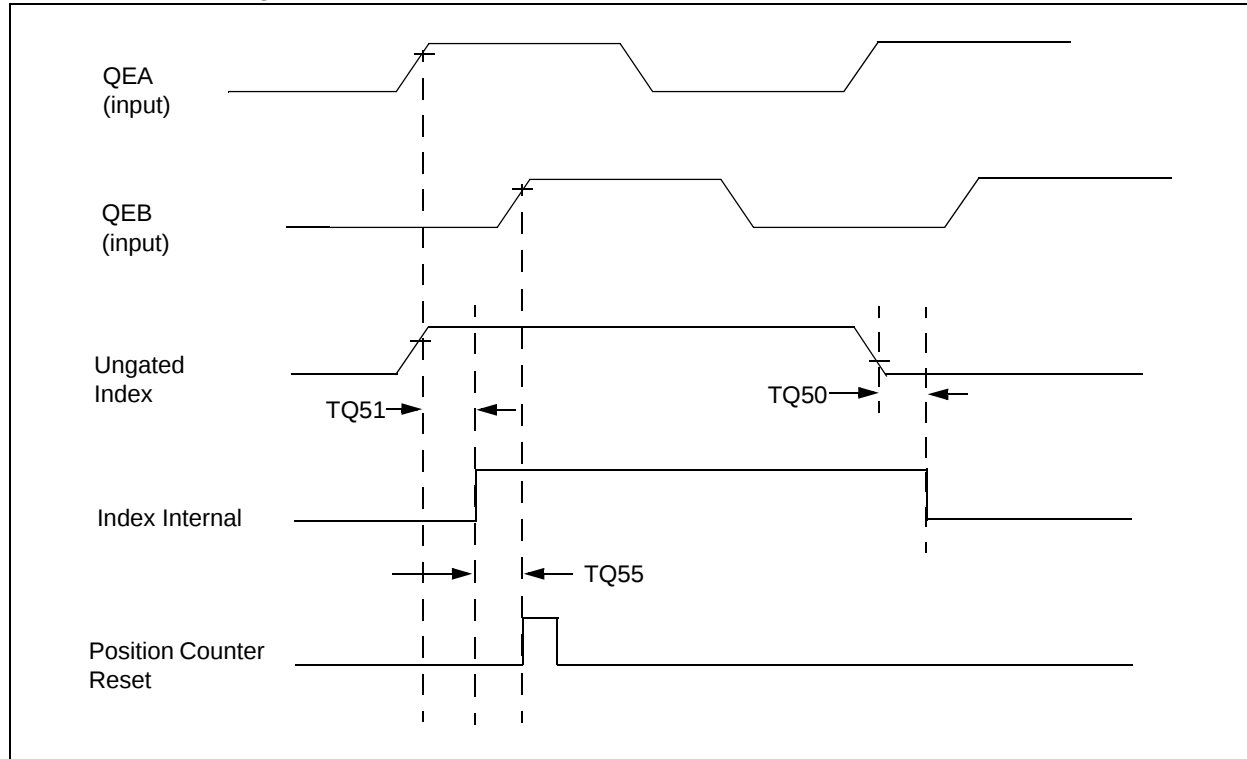


TABLE 22-31: QEI INDEX PULSE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Max	Units	Conditions
TQ50	TqIL	Filter Time to Recognize Low, with Digital Filter	3 * N * TcY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 (Note 2)
TQ51	TqiH	Filter Time to Recognize High, with Digital Filter	3 * N * TcY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 (Note 2)
TQ55	Tqidxr	Index Pulse Recognized to Position Counter Reset (Ungated Index)	3 TcY	—	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

- 2:** Alignment of Index Pulses to QEA and QEB is shown for Position Counter reset timing only. Shown for forward direction only (QEA leads QEB). Same timing applies for reverse direction (QEA lags QEB) but Index Pulse recognition occurs on falling edge.

FIGURE 22-16: SPI MODULE MASTER MODE (CKE = 0) TIMING CHARACTERISTICS

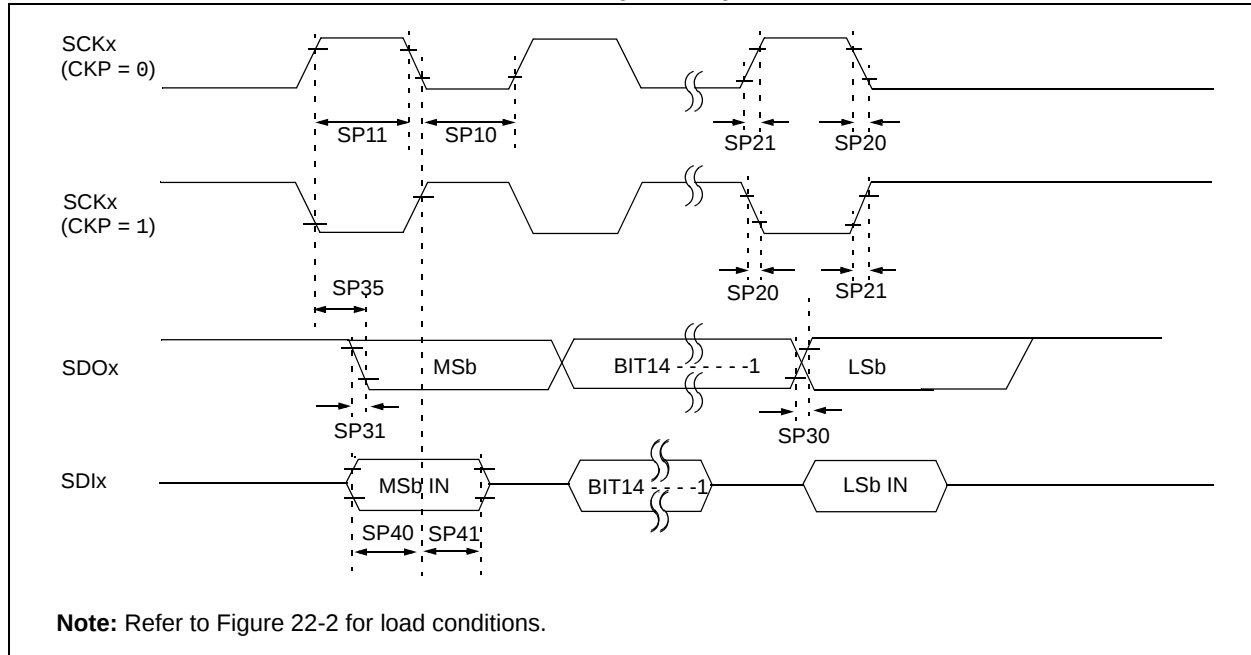


TABLE 22-32: SPI MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Typ ⁽²⁾	Max	Units	Conditions
SP10	TscL	SCKx Output Low Time ⁽³⁾	Tcy/2	—	—	ns	See Note 3
SP11	TscH	SCKx Output High Time ⁽³⁾	Tcy/2	—	—	ns	See Note 3
SP20	TscF	SCKx Output Fall Time ⁽⁴⁾	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time ⁽⁴⁾	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time ⁽⁴⁾	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time ⁽⁴⁾	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	30	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	20	—	—	ns	—
SP41	Tsch2diL, TschL2diL	Hold Time of SDIx Data Input to SCKx Edge	20	—	—	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 5V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCK is 100 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI pins.

FIGURE 22-18: SPI MODULE SLAVE MODE (CKE = 0) TIMING CHARACTERISTICS

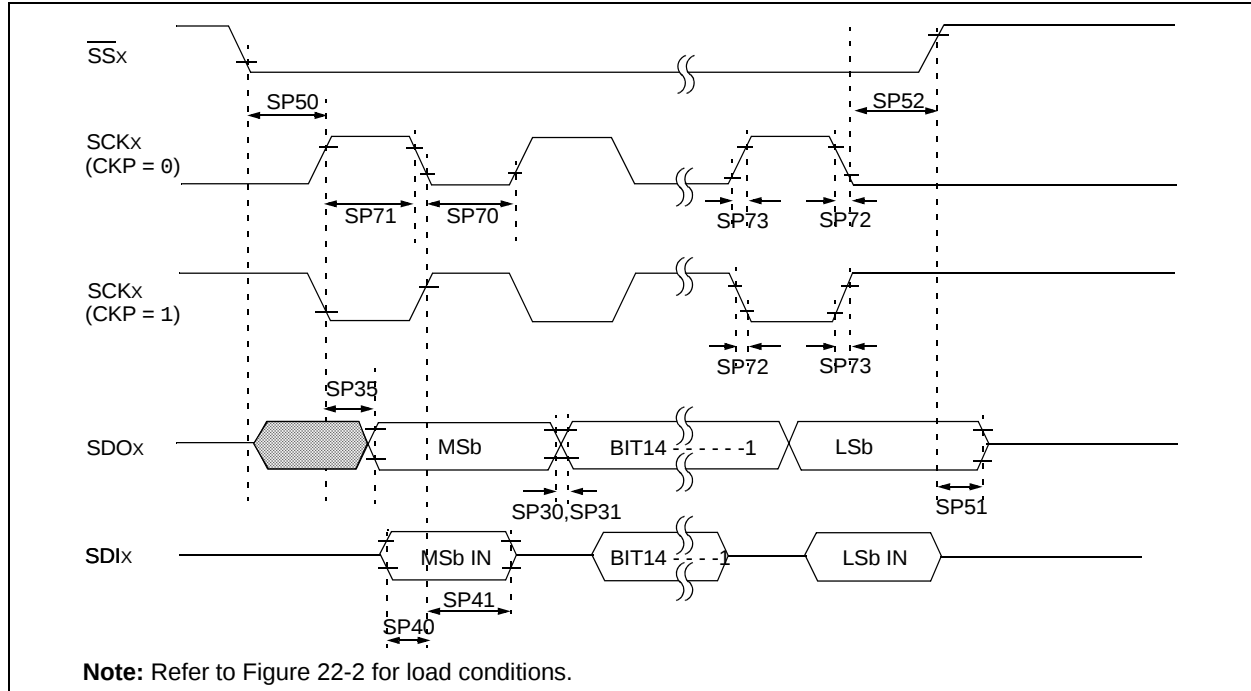


TABLE 22-34: SPI MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Typ ⁽²⁾	Max	Units	Conditions
SP70	TscL	SCKx Input Low Time	30	—	—	ns	See Note 3
SP71	TschH	SCKx Input High Time	30	—	—	ns	See Note 3
SP72	TscF	SCKx Input Fall Time ⁽³⁾	—	10	25	ns	—
SP73	TscR	SCKx Input Rise Time ⁽³⁾	—	10	25	ns	—
SP30	TdoF	SDOx Data Output Fall Time ⁽³⁾	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time ⁽³⁾	—	—	—	ns	See parameter DO31
SP35	Tsch2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	30	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	20	—	—	ns	—
SP41	Tsch2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	20	—	—	ns	—
SP50	TssL2scH, TssL2scL	SSx↓ to SCKx↑ or SCKx↓ Input	120	—	—	ns	—
SP51	TssH2doZ	SSx↑ to SDOx Output High-Impedance ⁽³⁾	10	—	50	ns	—
SP52	Tsch2ssH, TscL2ssH	SSx after SCK Edge	1.5 Tcy + 40	—	—	ns	—

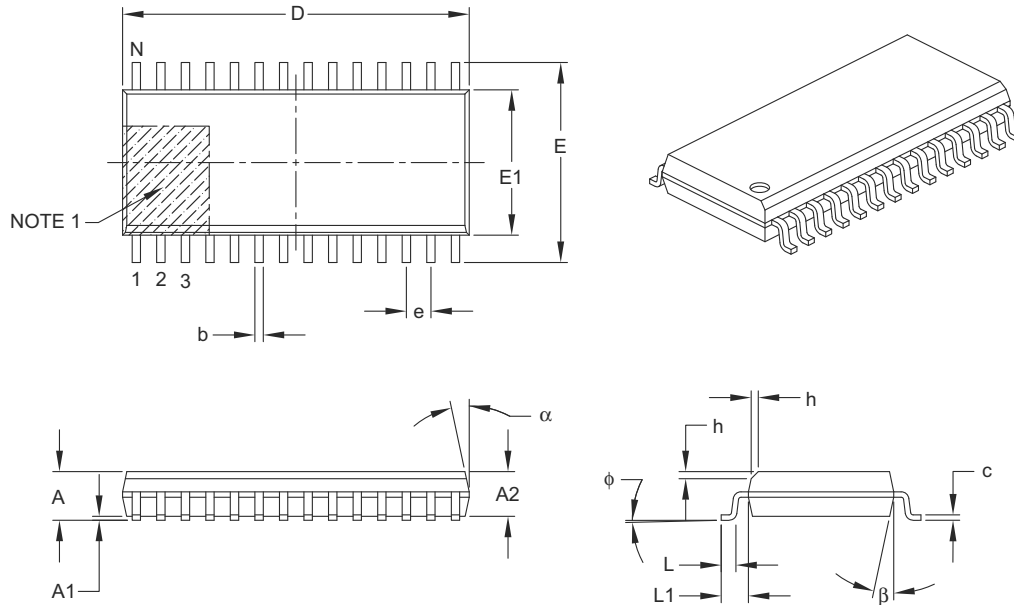
Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 5V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: Assumes 50 pF load on all SPI pins.

28-Lead Plastic Small Outline (SO) – Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	1.27 BSC		
Overall Height	A	–	–	2.65
Molded Package Thickness	A2	2.05	–	–
Standoff §	A1	0.10	–	0.30
Overall Width	E	10.30 BSC		
Molded Package Width	E1	7.50 BSC		
Overall Length	D	17.90 BSC		
Chamfer (optional)	h	0.25	–	0.75
Foot Length	L	0.40	–	1.27
Footprint	L1	1.40 REF		
Foot Angle Top	φ	0°	–	8°
Lead Thickness	c	0.18	–	0.33
Lead Width	b	0.31	–	0.51
Mold Draft Angle Top	α	5°	–	15°
Mold Draft Angle Bottom	β	5°	–	15°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-052B

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